

# ESP32-H2-MINI-1

# ESP32-H2-MINI-1U

Datasheet Version 1.0

Bluetooth® Low Energy and IEEE 802.15.4 module

Built around ESP32-H2 series of SoCs, RISC-V single-core 32-bit microprocessor

2 MB or 4 MB flash in chip package

19 GPIOs

On-board PCB antenna or external antenna connector



ESP32-H2-MINI-1



ESP32-H2-MINI-1U



# 1 Module Overview

## Note:

Check the link or the QR code to make sure that you use the latest version of this document:  
[https://espressif.com/documentation/esp32-h2-mini-1\\_mini-1u\\_datasheet\\_en.pdf](https://espressif.com/documentation/esp32-h2-mini-1_mini-1u_datasheet_en.pdf)



## 1.1 Features

### CPU and On-Chip Memory

- ESP32-H2 embedded, RISC-V single-core 32-bit microprocessor, up to 96 MHz
- 128 KB ROM
- 320 KB SRAM
- 4 KB LP Memory
- 2 MB or 4 MB in-package flash

### Bluetooth®

- Bluetooth Low Energy (Bluetooth 5.3 certified)
- Bluetooth mesh
- Bluetooth Low Energy long range (Coded PHY, 125 Kbps and 500 Kbps)
- Bluetooth Low Energy high speed (2 Mbps)
- Bluetooth Low Energy advertising extensions and multiple advertising sets
- Simultaneous operation of Broadcaster, Observer, Central, and Peripheral devices
- Multiple connections
- LE power control

### IEEE 802.15.4

- IEEE Standard 802.15.4-2015 compliant
- Supports 250 Kbps data rate in 2.4 GHz band and OQPSK PHY
- Supports Thread 1.3
- Supports Zigbee 3.0

- Supports Matter
- Supports other application-layer protocols (HomeKit, MQTT, etc)

### Peripherals

- Up to 19 GPIOs
  - 3 strapping pins
- I2C, I2S, SPI, UART, ADC, LED PWM, ETM, GDMA, PCNT, PARLIO, RMT, TWAI®, MCPWM, USB Serial/JTAG, temperature sensor, general-purpose timers, system timer, watchdog timer

### Integrated Components on Module

- 32 MHz crystal oscillator

### Antenna Options

- ESP32-H2-MINI-1: On-board PCB antenna
- ESP32-H2-MINI-1U: External antenna via a connector

### Operating Conditions

- Operating voltage/Power supply: 3.0~3.6 V
- Operating ambient temperature:
  - 85 °C version: -40~85 °C
  - 105 °C version: -40~105 °C

### Certification

- RF certification: See [certificates](#)

## 1.2 Series Comparison

ESP32-H2-MINI-1 and ESP32-H2-MINI-1U are two powerful, generic Bluetooth® Low Energy and IEEE 802.15.4 combo module that have a rich set of peripherals. They are an ideal choice for a wide variety of application scenarios related to Internet of Things (IoT), such as embedded systems, smart home, wearable electronics, etc.

ESP32-H2-MINI-1 comes with a PCB antenna. ESP32-H2-MINI-1U comes with a connector for an external antenna.

Both ESP32-H2-MINI-1 and ESP32-H2-MINI-1U come in two versions:

- 85 °C version
- 105 °C version

The two versions only vary in maximum ambient temperature and flash part number. In this datasheet unless otherwise stated, ESP32-H2-MINI-1 and ESP32-H2-MINI-1U refer to both 85 °C and 105 °C versions.

The series comparison for the two modules is as follows:

**Table 1: ESP32-H2-MINI-1 Series Comparison** <sup>1</sup>

Ordering Code	Flash <sup>4</sup>	Ambient Temp. <sup>2</sup> (°C)	Size <sup>3</sup> (mm)
ESP32-H2-MINI-1-H2	2 MB (Quad SPI)	-40~105	13.2 × 16.6 × 2.4
ESP32-H2-MINI-1-H4	4 MB (Quad SPI)	-40~105	
ESP32-H2-MINI-1-N4	4 MB (Quad SPI)	-40~85	

<sup>1</sup> This table shares the same notes presented in Table 2 below.

**Table 2: ESP32-H2-MINI-1U Series Comparison**

Ordering Code	Flash <sup>4</sup>	Ambient Temp. <sup>2</sup> (°C)	Size <sup>3</sup> (mm)
ESP32-H2-MINI-1U-H2	2 MB (Quad SPI)	-40~105	13.2 × 12.5 × 2.4
ESP32-H2-MINI-1U-H4	4 MB (Quad SPI)	-40~105	
ESP32-H2-MINI-1U-N4	4 MB (Quad SPI)	-40~85	

<sup>2</sup> Ambient temperature specifies the recommended temperature range of the environment immediately outside the Espressif module.

<sup>3</sup> For details, refer to Section [10.1 Module Dimensions](#).

<sup>4</sup> The flash is integrated in the chip's package. The flash supports:

- More than 100,000 program/erase cycles
- More than 20 years data retention time

Please note that this table is not updated to template v0.8 yet. May update later.

At the core of this module is ESP32-H2, a 32-bit RISC-V single-core CPU that operates at up to 96 MHz.

**Note:**

\* For more information on ESP32-H2, please refer to [ESP32-H2 Series Datasheet](#).

## 1.3 Applications

- Smart Home
- Industrial Automation
- Health Care
- Consumer Electronics
- Smart Agriculture
- Matter Solutions
- Service Robot
- Generic Low-power IoT Sensor Hubs
- Generic Low-power IoT Data Loggers

# Contents

<b>1</b>	<b>Module Overview</b>	<b>2</b>
1.1	Features	2
1.2	Series Comparison	3
1.3	Applications	4
<b>2</b>	<b>Block Diagram</b>	<b>9</b>
<b>3</b>	<b>Pin Definitions</b>	<b>10</b>
3.1	Pin Layout	10
3.2	Pin Description	10
<b>4</b>	<b>Boot Configurations</b>	<b>12</b>
4.1	Chip Boot Mode Control	13
4.2	ROM Messages Printing Control	13
4.3	JTAG Signal Source Control	14
<b>5</b>	<b>Peripherals</b>	<b>16</b>
5.1	Peripheral Overview	16
5.2	Peripheral Description	16
5.2.1	Connectivity Interfaces	16
5.2.1.1	UART Controller	16
5.2.1.2	SPI Controller	17
5.2.1.3	I2C Controller	18
5.2.1.4	I2S Controller	18
5.2.1.5	Pulse Count Controller	19
5.2.1.6	USB Serial/JTAG Controller	19
5.2.1.7	Two-wire Automotive Interface	20
5.2.1.8	LED PWM Controller	20
5.2.1.9	Motor Control PWM	21
5.2.1.10	Remote Control Peripheral	22
5.2.1.11	Parallel IO Controller	23
5.2.2	Analog Signal Processing	23
5.2.2.1	SAR ADC	23
5.2.2.2	Temperature Sensor	24
5.2.2.3	Analog PAD Voltage Comparator	24
<b>6</b>	<b>Electrical Characteristics</b>	<b>25</b>
6.1	Absolute Maximum Ratings	25
6.2	Recommended Operating Conditions	25
6.3	DC Characteristics (3.3 V, 25 °C)	25
6.4	Current Consumption Characteristics	26
6.4.1	Current Consumption in Active Mode	26
6.4.2	Current Consumption in Other Modes	27

<b>7</b>	<b>RF Characteristics</b>	28
7.1	Bluetooth 5 (LE) Radio	28
7.1.1	Bluetooth LE RF Transmitter (TX) Characteristics	28
7.1.2	Bluetooth LE RF Receiver (RX) Characteristics	30
7.2	802.15.4 Radio	32
7.2.1	802.15.4 RF Transmitter (TX) Characteristics	32
7.2.2	802.15.4 RF Receiver (RX) Characteristics	32
<b>8</b>	<b>Module Schematics</b>	33
<b>9</b>	<b>Peripheral Schematics</b>	35
<b>10</b>	<b>Physical Dimensions</b>	36
10.1	Module Dimensions	36
10.2	Dimensions of External Antenna Connector	37
<b>11</b>	<b>PCB Layout Recommendations</b>	38
11.1	PCB Land Pattern	38
11.2	Module Placement for PCB Design	39
<b>12</b>	<b>Product Handling</b>	40
12.1	Storage Conditions	40
12.2	Electrostatic Discharge (ESD)	40
12.3	Soldering Profile	40
12.3.1	Reflow Profile	40
12.4	Ultrasonic Vibration	41
	<b>Related Documentation and Resources</b>	42
	<b>Revision History</b>	43

## List of Tables

1	ESP32-H2-MINI-1 Series Comparison <sup>1</sup>	3
2	ESP32-H2-MINI-1U Series Comparison	3
3	Pin Definitions	11
4	Default Configuration of Strapping Pins	12
5	Description of Timing Parameters for the Strapping Pins	13
6	Chip Boot Mode Control	13
7	UART0 ROM Message Printing Control	14
8	USB Serial/JTAG ROM Message Printing Control	14
9	JTAG Signal Source Control	15
10	Absolute Maximum Ratings	25
11	Recommended Operating Conditions	25
12	DC Characteristics (3.3 V, 25 °C)	25
13	Current Consumption for Bluetooth LE in Active Mode	26
14	Current Consumption for 802.15.4 in Active Mode	26
15	Current Consumption in Modem-sleep Mode	27
16	Current Consumption in Low-Power Modes	27
17	Bluetooth LE RF Characteristics	28
18	Bluetooth LE - Transmitter Characteristics - 1 Mbps	28
19	Bluetooth LE - Transmitter Characteristics - 2 Mbps	28
20	Bluetooth LE - Transmitter Characteristics - 125 Kbps	29
21	Bluetooth LE - Transmitter Characteristics - 500 Kbps	29
22	Bluetooth LE - Receiver Characteristics - 1 Mbps	30
23	Bluetooth LE - Receiver Characteristics - 2 Mbps	30
24	Bluetooth LE - Receiver Characteristics - 125 Kbps	31
25	Bluetooth LE - Receiver Characteristics - 500 Kbps	31
26	802.15.4 RF Characteristics	32
27	802.15.4 Transmitter Characteristics - 250 Kbps	32
28	802.15.4 Receiver Characteristics - 250 Kbps	32

## List of Figures

1	ESP32-H2-MINI-1 Block Diagram	9
2	ESP32-H2-MINI-1U Block Diagram	9
3	Pin Layout (Top View)	10
4	Visualization of Timing Parameters for the Strapping Pins	13
5	ESP32-H2-MINI-1 Schematics	33
6	ESP32-H2-MINI-1U Schematics	34
7	Peripheral Schematics	35
8	ESP32-H2-MINI-1 Physical Dimensions	36
9	ESP32-H2-MINI-1U Physical Dimensions	36
10	Dimensions of External Antenna Connector	37
11	ESP32-H2-MINI-1 Recommended PCB Land Pattern	38
12	ESP32-H2-MINI-1U Recommended PCB Land Pattern	39
13	Reflow Profile	41

## 2 Block Diagram

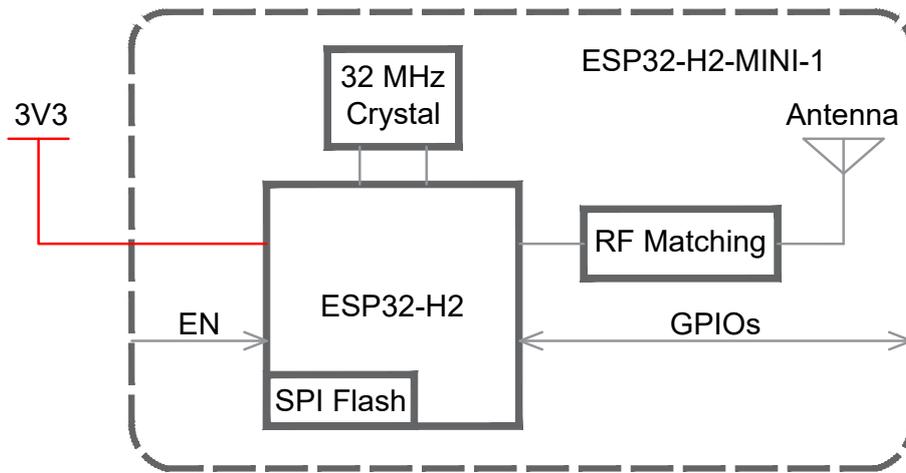


Figure 1: ESP32-H2-MINI-1 Block Diagram

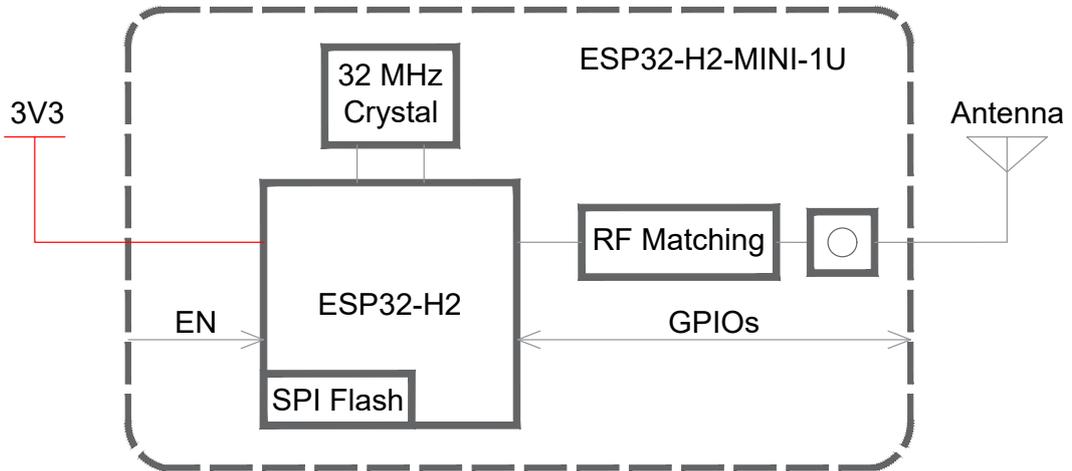


Figure 2: ESP32-H2-MINI-1U Block Diagram



Table 3: Pin Definitions

Name	No.	Type <sup>1</sup>	Function
GND	1, 2, 11, 14, 36~53	P	Ground
3V3	3	P	Power supply
NC	4, 7, 17, 28, 29, 32~35	—	NC
IO2	5	I/O/T	GPIO2, FSPIWP, ADC1_CH1, <b>MTMS</b>
IO3	6	I/O/T	GPIO3, FSPIHD, ADC1_CH2, <b>MTDO</b>
EN	8	I	High: on, enables the chip. Low: off, the chip powers off. Note: Do not leave the EN pin floating.
IO0	9	I/O/T	<b>GPIO0</b> , FSPIQ
IO1	10	I/O/T	<b>GPIO1</b> , FSPICS0, ADC1_CHO
GND	11	P	Ground
IO13	12	I/O/T	<b>GPIO13</b> , XTAL_32K_P
IO14	13	I/O/T	<b>GPIO14</b> , XTAL_32K_N
GND	14	P	Ground
VBAT	15	P	Connected to internal 3V3 power supply (Default) or external battery power supply (3.0 ~ 3.6 V).
IO12	16	I/O/T	<b>GPIO12</b>
IO4	18	I/O/T	GPIO4, FSPICLK, ADC1_CH3, <b>MTCK</b>
IO5	19	I/O/T	GPIO5, FSPID, ADC1_CH4, <b>MTDI</b>
IO10	20	I/O/T	<b>GPIO10</b> , ZCD0
IO11	21	I/O/T	<b>GPIO11</b> , ZCD1
IO8	22	I/O/T	<b>GPIO8</b>
IO9	23	I/O/T	<b>GPIO9</b>
IO22	24	I/O/T	<b>GPIO22</b>
IO25	25	I/O/T	<b>GPIO25</b> , FSPICS3
IO26	26	I/O/T	GPIO26, FSPICS4, <b>USB_D-</b>
IO27	27	I/O/T	GPIO27, FSPICS5, <b>USB_D+</b>
RXD0	30	I/O/T	GPIO23, FSPICS1, <b>UORXD</b>
TXD0	31	I/O/T	GPIO24, FSPICS2, <b>UOTXD</b>

<sup>1</sup> P: power supply; I: input; O: output; T: high impedance.

## 4 Boot Configurations

**Note:**

The content below is excerpted from [ESP32-H2 Series Datasheet](#) > Section *Boot Configurations via Strapping Pins and eFuses*. For the strapping pin mapping between the chip and modules, please refer to Chapter 10 *Physical Dimensions*.

The chip allows for configuring the following boot parameters through strapping pins, eFuse bits, and registers at power-up or a hardware reset, without microcontroller interaction.

- **Chip boot mode**
  - Strapping pin: GPIO8 and GPIO9
- **ROM message printing**
  - Strapping pin: GPIO8
  - eFuse bits: EFUSE\_UART\_PRINT\_CONTROL and EFUSE\_DIS\_USB\_SERIAL\_JTAG\_ROM\_PRINT
  - Register: LP\_AON\_STORE4\_REG[0]
- **JTAG signal source**
  - Strapping pin: GPIO25
  - eFuse bits: EFUSE\_DIS\_PAD\_JTAG, EFUSE\_DIS\_USB\_JTAG, and EFUSE\_JTAG\_SEL\_ENABLE

The default values of all the above eFuse bits are 0, which means that they are not burnt. Given that eFuse is one-time programmable, once an eFuse bit is programmed to 1, it can never be reverted to 0. For how to program eFuse bits, please refer to [ESP32-H2 Technical Reference Manual](#) > Chapter *eFuse Controller*.

The default values of the strapping pins, namely the logic levels, are determined by pins' internal weak pull-up/pull-down resistors at reset if the pins are not connected to any circuit, or connected to an external high-impedance circuit.

**Table 4: Default Configuration of Strapping Pins**

Strapping Pin	Default Configuration	Bit Value
GPIO8	Floating	—
GPIO9	Weak pull-up	1
GPIO25	Floating	—

To change the bit values, the strapping pins should be connected to external pull-down/pull-up resistances. If the ESP32-H2 is used as a device by a host MCU, the strapping pin voltage levels can also be controlled by the host MCU.

All strapping pins have latches. At system reset, the latches sample the bit values of their respective strapping pins and store them until the chip is powered down or shut down. The states of latches cannot be changed in any other way. It makes the strapping pin values available during the entire chip operation, and the pins are freed up to be used as regular IO pins after reset.

The timing of signals connected to the strapping pins should adhere to the *setup time* and *hold time* specifications in Table 5 and Figure 4.

Table 5: Description of Timing Parameters for the Strapping Pins

Parameter	Description	Min (ms)
$t_{SU}$	Setup time is the time reserved for the power rails to stabilize before the CHIP_EN pin is pulled high to activate the chip.	0
$t_H$	Hold time is the time reserved for the chip to read the strapping pin values after CHIP_EN is already high and before these pins start operating as regular IO pins.	3

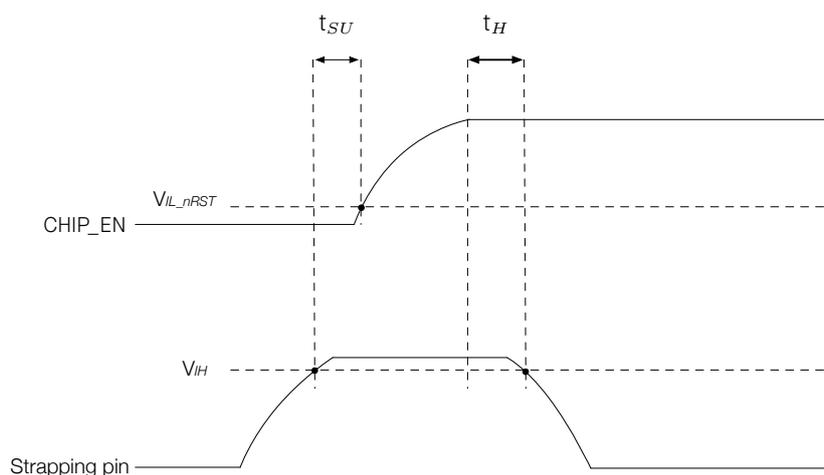


Figure 4: Visualization of Timing Parameters for the Strapping Pins

## 4.1 Chip Boot Mode Control

GPI08 and GPI09 control the boot mode after the reset is released. See Table 6 *Chip Boot Mode Control*.

Table 6: Chip Boot Mode Control

Boot Mode <sup>1</sup>	GPI08	GPI09
SPI Boot	Any value	<b>1</b>
Joint Download Boot <sup>2</sup>	1	0

<sup>1</sup> **Bold** marks the default value and configuration.

<sup>2</sup> Joint Download Boot mode supports the following download methods:

- USB Download Boot
  - USB-Serial-JTAG Download Boot
- UART Download Boot

## 4.2 ROM Messages Printing Control

During the boot process, ROM message printing is enabled if LP\_AON\_STORE4\_REG[0] is 0 (default), and disabled if LP\_AON\_STORE4\_REG[0] is 1. When ROM message printing is enabled, the messages can be printed to:

- **(Default) UART0 and USB Serial/JTAG controller**
- USB Serial/JTAG controller
- UART0

EFUSE\_UART\_PRINT\_CONTROL, LP\_AON\_STORE4\_REG[0], and GPIO8 control ROM messages printing to **UART0** as shown in Table 7 *UART0 ROM Message Printing Control*.

**Table 7: UART0 ROM Message Printing Control**

UART0 ROM Message Printing <sup>1</sup>	LP_AON_STORE4_REG[0]	EFUSE_UART_PRINT_CONTROL	GPIO8
<b>Enabled</b>	<b>0</b>	<b>0</b>	Ignored
		1	0
		2	1
Disabled	<b>0</b>	1	1
		2	0
		3	Ignored
	<b>1</b>	Ignored	Ignored

<sup>1</sup> **Bold** marks the default value and configuration.

EFUSE\_DIS\_USB\_SERIAL\_JTAG\_ROM\_PRINT controls the printing to **USB Serial/JTAG controller** as shown in Table 8 *USB Serial/JTAG ROM Message Printing Control*.

**Table 8: USB Serial/JTAG ROM Message Printing Control**

USB Serial/JTAG ROM Message Printing Control <sup>1</sup>	LP_AON_STORE4_REG[0]	EFUSE_DIS_USB_SERIAL_JTAG_ROM_PRINT
<b>Enabled</b>	<b>0</b>	<b>0</b>
Disabled	0	1
	1	Ignored

<sup>1</sup> **Bold** marks the default value and configuration.

### 4.3 JTAG Signal Source Control

The strapping pin GPIO25 can be used to control the source of JTAG signals during the early boot process. This pin does not have any internal pull resistors and the strapping value must be controlled by the external circuit that cannot be in a high impedance state.

As Table 9 shows GPIO25 is used in combination with EFUSE\_DIS\_PAD\_JTAG, EFUSE\_DIS\_USB\_JTAG, and EFUSE\_JTAG\_SEL\_ENABLE.

Table 9: JTAG Signal Source Control

JTAG Signal Source <sup>1</sup>	EFUSE_DIS_PAD_JTAG	EFUSE_DIS_USB_JTAG	EFUSE_STRAP_JTAG_SEL_ENABLE	GPIO25
<b>USB Serial/JTAG Controller</b>	<b>0</b>	<b>0</b>	<b>0</b>	Ignored
JTAG pins <sup>2</sup>			1	0
USB Serial/JTAG Controller				1
JTAG pins <sup>2</sup>	0	1	Ignored	Ignored
USB Serial/JTAG Controller	1	0	Ignored	Ignored
JTAG is disabled	1	1	Ignored	Ignored

<sup>1</sup> **Bold** marks the default value and configuration.

<sup>2</sup> JTAG pins refer to MTDI, MTCK, MTMS, and MTDO.

## 5 Peripherals

### 5.1 Peripheral Overview

ESP32-H2 integrates a rich set of peripherals including SPI, I2S, UART, I2C, LED PWM, ADC, TWAI®, temperature sensor, etc.

To learn more about on-chip components, please refer to [ESP32-H2 Series Datasheet](#) > Section *Functional Description*.

**Note:**

The content below is sourced from [ESP32-H2 Series Datasheet](#) > Section *Peripherals*. Some information may not be applicable to ESP32-H2-MINI-1 and ESP32-H2-MINI-1U as not all the IO signals are exposed on the module.

To learn more about peripheral signals, please refer to [ESP32-H2 Technical Reference Manual](#) > Section *Peripheral Signal List*.

### 5.2 Peripheral Description

This section describes the chip's peripheral capabilities, covering connectivity interfaces and on-chip sensors that extend its functionality.

#### 5.2.1 Connectivity Interfaces

This subsection describes the connectivity interfaces on the chip that enable communication and interaction with external devices and networks.

##### 5.2.1.1 UART Controller

The UART Controller in the ESP32-H2 chip facilitates the transmission and reception of asynchronous serial data between the chip and external UART devices. It consists of two UARTs in the system.

#### Feature List

- Programmable baud rates up to 5 MBaud
- 260 x 8 bit RAM shared by TX FIFOs and RX FIFOs
- Support for various lengths of data bits and stop bits
- Parity bit support
- Special character AT\_CMD detection
- RS485 protocol support
- IrDA protocol support
- High-speed data communication using GDMA
- Receive timeout feature
- UART as the wake-up source

- Software and hardware flow control

### Pin Assignment

The pins connected to receive and transmit signals (UORXD and UOTXD) for **UART0** are multiplexed with GPIO23 ~ GPIO24 and FSPICS1 ~ FSPICS2 via IO MUX. Other signals can be routed to any GPIOs via the GPIO matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.2 SPI Controller

ESP32-H2 has the following SPI interfaces:

- **SPI0/SPI1** are reserved for system use.
- **SPI2** is a general-purpose SPI (GP-SPI) controller with access to general-purpose DMA channels.

#### Features of SPI2

- Supports operation as a master or slave
- Support for DMA
- Supports Single SPI, Dual SPI, Quad SPI, QPI modes
- Configurable clock polarity (CPOL) and phase (CPHA)
- Configurable clock frequency
- Data transmission is in bytes
- Configurable read and write data bit order: most-significant bit (MSB) first, or least-significant bit (LSB) first
- As a master
  - Supports 2-line full-duplex communication with clock frequency up to 48 MHz
  - Supports 1-, 2-, 4-line half-duplex communication with clock frequency up to 48 MHz
  - Provides six FSPICS... pins for connection with six independent SPI slaves
  - Configurable CS setup time and hold time
- As a slave
  - Supports 2-line full-duplex communication with clock frequency up to 32 MHz
  - Supports 1-, 2-, 4-line half-duplex communication with clock frequency up to 32 MHz

#### Pin Assignment

- Via IO MUX  
For SPI2, the pins for data and clock signals are multiplexed with GPIO0, GPIO2 ~ GPIO5, and JTAG interface via the IO MUX. The pins for chip select signals are multiplexed with GPIO1, GPIO23 ~ GPIO27, UART0 interface, and USB interface via the IO MUX.

- Via GPIO Matrix

The pins for SPI2 can be chosen from any GPIOs via the GPIO matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.3 I2C Controller

The I2C Controller supports communication between the master and slave devices using the I2C bus.

#### Feature List

- Two I2C controllers
- Communication with multiple external devices
- Master and slave modes
- Standard mode (100 Kbit/s) and fast mode (400 Kbit/s)
- SCL clock stretching in slave mode
- Programmable digital noise filtering
- Support for 7-bit and 10-bit addressing, as well as dual address mode

#### Pin Assignment

The pins used for I2C can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.4 I2S Controller

The I2S Controller in the ESP32-H2 chip provides a flexible communication interface for streaming digital data in multimedia applications, particularly digital audio applications.

#### Feature List

- Master mode and slave mode
- Full-duplex and half-duplex communications
- Separate TX and RX units that can work independently or simultaneously
- A variety of audio standards supported:
  - TDM Philips standard
  - TDM MSB alignment standard
  - TDM PCM standard
  - PDM standard
- PCM-to-PDM TX interface

- Configurable high-precision BCK clock, with frequency up to 40 MHz
  - Sampling frequencies can be 8 kHz, 16 kHz, 32 kHz, 44.1 kHz, 48 kHz, 88.2 kHz, 96 kHz, 128 kHz, etc.
- 8-/16-/24-/32-bit data communication
- Direct Memory Access (DMA)
- A-law and  $\mu$ -law compression/decompression algorithms for improved signal-to-quantization noise ratio
- Flexible data format control

### Pin Assignment

The pins for the I2S Controller can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.5 Pulse Count Controller

The Pulse Count Controller (PCNT) is designed to count input pulses by tracking the rising and falling edges of the input pulse signal.

#### Feature List

- Four independent pulse counters with two channels each
- Counter modes: increment, decrement, or disable
- Glitch filtering for input pulse signals and control signals
- Selection between counting on rising or falling edges of the input pulse signal

### Pin Assignment

The pins for the Pulse Count Controller can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.6 USB Serial/JTAG Controller

The USB Serial/JTAG controller in the ESP32-H2 chip provides an integrated solution for communicating to the chip over a standard USB CDC-ACM serial port as well as a convenient method for JTAG debugging. It eliminates the need for external chips or JTAG adapters, saving space and reducing cost.

#### Feature List

- USB 2.0 full speed compliant, capable of up to 12 Mbit/s transfer speed (Note that this controller does not support the faster 480 Mbit/s high-speed transfer mode)
- CDC-ACM virtual serial port and JTAG adapter functionality
- CDC-ACM:

- CDC-ACM adherent serial port emulation (plug-and-play on most modern OSes)
- Host controllable chip reset and entry into download mode
- JTAG adapter functionality:
  - Fast communication with CPU debugging core using a compact representation of JTAG instructions
- Internal PHY

### Pin Assignment

The pins USB\_D+ and USB\_D- for the USB Serial/JTAG Controller are multiplexed with GPIO26 ~ GPIO27 and FSPICS4 ~ FSPICS5 via IO MUX.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.7 Two-wire Automotive Interface

The Two-wire Automotive Interface (TWAI<sup>®</sup>) is a multi-master, multi-cast communication protocol designed for automotive applications. The TWAI controller facilitates the communication based on this protocol.

#### Feature List

- Compatible with ISO 11898-1 protocol (CAN Specification 2.0)
- Standard frame format (11-bit ID) and extended frame format (29-bit ID)
- Bit rates from 1 Kbit/s to 1 Mbit/s
- Multiple modes of operation: Normal, Listen Only, and Self-Test (no acknowledgment required)
- Special transmissions: Single-shot and Self Reception
- Acceptance filter (single and dual filter modes)
- Error detection and handling: error counters, configurable error warning limit, error code capture, arbitration lost capture, automatic transceiver standby

### Pin Assignment

The pins for the Two-wire Automotive Interface can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.8 LED PWM Controller

The LED PWM Controller (LEDC) is designed to generate PWM signals for LED control.

#### Feature List

- Six independent PWM generators
- Maximum PWM duty cycle resolution of 20 bits

- Four independent timers with 20-bit counters, configurable fractional clock dividers and counter overflow values
- Adjustable phase of PWM signal output
- PWM duty cycle dithering
- Automatic duty cycle fading
  - Linear duty cycle fading — only one duty cycle range
  - Gamma curve fading — up to 16 duty cycle ranges for each PWM generator, with independently configured fading direction (increase or decrease), fading amount, number of fades, and fading frequency
- PWM signal output in low-power mode (Light-sleep mode)
- Event generation and task response achieved by the Event Task Matrix (ETM)

### Pin Assignment

The pins for the LED PWM Controller can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.9 Motor Control PWM

The Motor Control Pulse Width Modulator (MCPWM) is designed for driving digital motors and smart light. The MCPWM is divided into five main modules: PWM timers, PWM operators, Capture module, Fault Detection module, and Event Task Matrix (ETM) module.

#### Feature List

- Three PWM timers for precise timing and frequency control
  - Every PWM timer has a dedicated 8-bit clock prescaler
  - The 16-bit counter in the PWM timer can work in count-up mode, count-down mode, or count-up-down mode
  - Hardware or software synchronization to trigger a reload on the PWM timer or the prescaler's restart, with selectable hardware synchronization source
- Three PWM operators for generating waveform pairs
  - Six PWM outputs to operate in several topologies
  - The control of the PWM signal can be updated asynchronously
  - Configurable dead time on rising and falling edges; each set up independently
  - Modulating of PWM output by high-frequency carrier signals, useful when gate drivers are insulated with a transformer
  - Period, time stamps, and important control registers have shadow registers with flexible updating methods

- Capture module for hardware-based signal processing
  - Speed measurement of rotating machinery
  - Measurement of elapsed time between position sensor pulses
  - Period and duty cycle measurement of pulse train signals
  - Decoding current or voltage amplitude derived from duty-cycle-encoded signals of current/voltage sensors
  - Three individual capture channels, each of which with a 32-bit time-stamp register
  - Selection of edge polarity and prescaling of input capture signals
  - The capture timer can sync with a PWM timer or external signals
- Fault Detection module
  - Programmable fault handling in both cycle-by-cycle mode and one-shot mode
  - A fault condition can force the PWM output to either high or low logic levels
- Event generation and task response achieved by the Event Task Matrix (ETM)

### Pin Assignment

The pins for the Motor Control PWM can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.10 Remote Control Peripheral

The Remote Control Peripheral (RMT) controls the transmission and reception of infrared remote control signals.

#### Feature List

- Four channels for sending and receiving infrared remote control signals
- Independent transmission and reception capabilities for each channel
- Support for Normal TX/RX mode, Wrap TX/RX mode, Continuous TX mode
- Modulation on TX pulses and Demodulation on RX pulses
- RX filtering for improved signal reception
- Ability to transmit data simultaneously on multiple channels
- Clock divider counter, state machine, and transmitter for each TX channel
- Clock divider counter, state machine, and receiver for each RX channel
- Default allocation of RAM blocks to channels based on channel number
- RAM containing 16-bit entries with “level” and “period” fields

## Pin Assignment

The pins for the Remote Control Peripheral can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.1.1 Parallel IO Controller

The Parallel IO Controller (PARLIO) in the ESP32-H2 chip enables data transfer between external devices and internal memory on a parallel bus through GDMA. It consists of a transmitter (TX unit) and a receiver (RX unit), making it a versatile interface for connecting various peripherals.

#### Feature List

- 1/2/4/8-bit configurable data bus width
- Full-duplex communication with 8-bit data bus width
- Bit reordering in 1/2/4-bit data bus width mode
- RX unit supports eight receive modes categorized into three major categories: Level Enable mode, Pulse Enable mode, and Software Enable mode
- TX unit can generate a valid signal aligned with TXD

## Pin Assignment

The pins for the Parallel IO Controller can be chosen from any GPIOs via the GPIO Matrix.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

## 5.2.2 Analog Signal Processing

This subsection describes components on the chip that sense and process real-world data.

### 5.2.2.1 SAR ADC

ESP32-H2 integrates a Successive Approximation Analog-to-Digital Converter (SAR ADC) to convert analog signals into digital representations.

#### Feature List

- 12-bit sampling resolution
- Analog voltage sampling from up to five pins
- Attenuation of input signals for voltage conversion
- Software-triggered one-time sampling
- Timer-triggered multi-channel scanning
- DMA continuous conversion for seamless data transfer

- Two filters with configurable filter coefficient
- Threshold monitoring which helps to trigger an interrupt
- Support for Event Task Matrix

### Pin Assignment

The pins for the SAR ADC are multiplexed with GPIO0 ~ GPIO5, JTAG interface, and SPI2 interface.

For more information about the pin assignment, see [ESP32-H2 Series Datasheet](#) > Section *IO Pins* and [ESP32-H2 Technical Reference Manual](#) > Chapter *IO MUX and GPIO Matrix*.

### 5.2.2.2 Temperature Sensor

The Temperature Sensor in the ESP32-H2 chip allows for real-time monitoring of temperature changes inside the chip.

#### Feature List

- Measurement range:  $-40^{\circ}\text{C}$  ~  $125^{\circ}\text{C}$
- Software triggering, wherein the data can be read continuously once triggered
- Hardware automatic triggering and temperature monitoring
- Configurable temperature offset based on the environment to improve the accuracy
- Adjustable measurement range
- Two automatic monitoring wake-up modes: absolute value mode and incremental value mode
- Support for Event Task Matrix

### 5.2.2.3 Analog PAD Voltage Comparator

ESP32-H2 integrates two analog voltage comparators. These comparators rely on special pads that support voltage comparison functionality to monitor voltage changes on these pads. Each analog voltage comparator has two pads associated with it, for the main voltage and the reference voltage respectively. The voltage comparison result generated by the analog voltage comparator can be used as Event Task Matrix (ETM) events to drive ETM tasks of other peripherals or trigger interrupts.

#### Feature List

- Voltage comparison
  - Configurable voltage comparison mode
  - Configurable reference voltage
- Interrupt upon changes of voltage comparison result
- ETM event generation

### Pin Assignment

The pins for the analog voltage pad comparators are multiplexed with GPIO10 ~ GPIO11.

## 6 Electrical Characteristics

### 6.1 Absolute Maximum Ratings

Stresses above those listed in Table 10 *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under Table 11 *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Table 10: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
VDD33	Power supply voltage	-0.3	3.6	V
T <sub>STORE</sub>	Storage temperature	-40	105	°C

### 6.2 Recommended Operating Conditions

Table 11: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDD33	Power supply voltage	3.0	3.3	3.6	V
I <sub>VDD</sub>	Current delivered by external power supply	0.5	—	—	A
T <sub>A</sub>	Operating ambient temperature	85 °C version	-40	85	°C
		105 °C version		105	

### 6.3 DC Characteristics (3.3 V, 25 °C)

Table 12: DC Characteristics (3.3 V, 25 °C)

Symbol	Parameter	Min	Typ	Max	Unit
C <sub>IN</sub>	Pin capacitance	—	2	—	pF
V <sub>IH</sub>	High-level input voltage	0.75 × VDD <sup>1</sup>	—	VDD <sup>1</sup> + 0.3	V
V <sub>IL</sub>	Low-level input voltage	-0.3	—	0.25 × VDD <sup>1</sup>	V
I <sub>IH</sub>	High-level input current	—	—	50	nA
I <sub>IL</sub>	Low-level input current	—	—	50	nA
V <sub>OH</sub> <sup>2</sup>	High-level output voltage	0.8 × VDD <sup>1</sup>	—	—	V
V <sub>OL</sub> <sup>2</sup>	Low-level output voltage	—	—	0.1 × VDD <sup>1</sup>	V
I <sub>OH</sub>	High-level source current (VDD <sup>1</sup> = 3.3 V, V <sub>OH</sub> ≥ 2.64 V, PAD_DRIVER = 3)	—	40	—	mA
I <sub>OL</sub>	Low-level sink current (VDD <sup>1</sup> = 3.3 V, V <sub>OL</sub> = 0.495 V, PAD_DRIVER = 3)	—	28	—	mA
R <sub>PU</sub>	Pull-up resistor	—	45	—	kΩ
R <sub>PD</sub>	Pull-down resistor	—	45	—	kΩ
V <sub>IH_nRST</sub>	Chip reset release voltage	0.75 × VDD <sup>1</sup>	—	VDD <sup>1</sup> + 0.3	V
V <sub>IL_nRST</sub>	Chip reset voltage	-0.3	—	0.25 × VDD <sup>1</sup>	V

<sup>1</sup> VDD is the I/O voltage for pins of a particular power domain.

<sup>2</sup> V<sub>OH</sub> and V<sub>OL</sub> are measured using high-impedance load.

## 6.4 Current Consumption Characteristics

### 6.4.1 Current Consumption in Active Mode

The current consumption measurements are taken with a 3.3 V supply at 25 °C ambient temperature.

TX current consumption is rated at a 100% duty cycle.

RX current consumption is rated when the peripherals are disabled and the CPU idle.

**Table 13: Current Consumption for Bluetooth LE in Active Mode**

Work Mode	RF Condition	Description	Peak (mA)
Active (RF working)	TX	Bluetooth LE @ 18.0 dBm	112
		Bluetooth LE @ 7.0 dBm	55
		Bluetooth LE @ -2.0 dBm	35
		Bluetooth LE @ -24.0 dBm	26
	RX	Bluetooth LE	25

**Table 14: Current Consumption for 802.15.4 in Active Mode**

Work Mode	RF Condition	Description	Peak (mA)
Active (RF working)	TX	802.15.4 @ 18.0 dBm	123
		802.15.4 @ 7.0 dBm	54
		802.15.4 @ -2.0 dBm	38
		802.15.4 @ -22.0 dBm	28
	RX	802.15.4	29

**Note:**

The content below is excerpted from *Section Power Consumption in Other Modes* in [ESP32-H2 Series Datasheet](#).

## 6.4.2 Current Consumption in Other Modes

The measurements below are applicable to ESP32-H2FH2 and ESP32-H2FH4.

**Table 15: Current Consumption in Modem-sleep Mode**

Work mode	Frequency (MHz)	Description	Typ <sup>1</sup> (mA)	
			All Peripheral Clocks Disabled	All Peripheral Clocks Enabled
Modem-sleep <sup>2</sup>	96	CPU running	10	17
		CPU in idle	6	13
	64	CPU running	8	13
		CPU in idle	5	10
	48	CPU running	7	11
		CPU in idle	5	9
	32	CPU running	4	8
		CPU in idle	3	7

<sup>1</sup> In practice, the current consumption might be different depending on which peripherals are enabled.

<sup>2</sup> In Modem-sleep mode, the current consumption might be higher when accessing flash.

**Table 16: Current Consumption in Low-Power Modes**

Work mode	Description	Typ (μA)
Light-sleep	CPU and wireless communication modules are powered down, peripheral clocks are disabled, and all GPIOs are high-impedance	85
	CPU, wireless communication modules and peripherals are powered down, and all GPIOs are high-impedance	25
Deep-sleep	LP timer and LP memory are powered on	7
Power off	CHIP_EN is set to low level, the chip is powered off	1

## 7 RF Characteristics

This section contains tables with RF characteristics of the Espressif product.

The RF data is measured at the antenna port, where RF cable is connected, including the front-end loss. The external antennas used for the tests on the modules with external antenna connectors have an impedance of 50  $\Omega$ .

Devices should operate in the center frequency range allocated by regional regulatory authorities. The target center frequency range and the target transmit power are configurable by software. See [ESP RF Test Tool and Test Guide](#) for instructions.

Unless otherwise stated, the RF tests are conducted with a 3.3 V ( $\pm 5\%$ ) supply at 25 °C ambient temperature.

### 7.1 Bluetooth 5 (LE) Radio

Table 17: Bluetooth LE RF Characteristics

Name	Description
Center frequency range of operating channel	2402~2480 MHz
RF transmit power range	-25.5~18.5 dBm

#### 7.1.1 Bluetooth LE RF Transmitter (TX) Characteristics

Table 18: Bluetooth LE - Transmitter Characteristics - 1 Mbps

Parameter	Description	Min	Typ	Max	Unit
Carrier frequency offset and drift	Max. $ f_n _{n=0, 1, 2, 3, \dots, k}$	—	2.3	—	kHz
	Max. $ f_0 - f_n _{n=2, 3, 4, \dots, k}$	—	1.3	—	kHz
	Max. $ f_n - f_{n-5} _{n=6, 7, 8, \dots, k}$	—	1.6	—	kHz
	$ f_1 - f_0 $	—	0.5	—	kHz
Modulation characteristics	$\Delta F1_{avg}$	—	250.3	—	kHz
	Min. $\Delta F2_{max}$ (for at least 99.9% of all $\Delta F2_{max}$ )	—	216.3	—	kHz
	$\Delta F2_{avg}/\Delta F1_{avg}$	—	0.91	—	—
In-band emissions	$\pm 2$ MHz offset	—	-30	—	dBm
	$\pm 3$ MHz offset	—	-34	—	dBm
	$> \pm 3$ MHz offset	—	-36	—	dBm

Table 19: Bluetooth LE - Transmitter Characteristics - 2 Mbps

Parameter	Description	Min	Typ	Max	Unit
Carrier frequency offset and drift	Max. $ f_n _{n=0, 1, 2, 3, \dots, k}$	—	4.7	—	kHz
	Max. $ f_0 - f_n _{n=2, 3, 4, \dots, k}$	—	1.4	—	kHz

Cont'd on next page

Table 19 – cont'd from previous page

Parameter	Description	Min	Typ	Max	Unit
	Max. $ f_n - f_{n-5} _{n=6, 7, 8, \dots k}$	—	1.4	—	kHz
	$ f_1 - f_0 $	—	0.6	—	kHz
Modulation characteristics	$\Delta F1_{avg}$	—	502.5	—	kHz
	Min. $\Delta F2_{max}$ (for at least 99.9% of all $\Delta F2_{max}$ )	—	491.8	—	kHz
	$\Delta F2_{avg}/\Delta F1_{avg}$	—	0.90	—	—
In-band emissions	$\pm 4$ MHz offset	—	-32	—	dBm
	$\pm 5$ MHz offset	—	-33	—	dBm
	$> \pm 5$ MHz offset	—	-36	—	dBm

Table 20: Bluetooth LE - Transmitter Characteristics - 125 Kbps

Parameter	Description	Min	Typ	Max	Unit
Carrier frequency offset and drift	Max. $ f_n _{n=0, 1, 2, 3, \dots k}$	—	1.5	—	kHz
	Max. $ f_0 - f_n _{n=1, 2, 3, \dots k}$	—	1.0	—	kHz
	$ f_0 - f_3 $	—	1.4	—	kHz
	Max. $ f_n - f_{n-3} _{n=7, 8, 9, \dots k}$	—	1.2	—	kHz
Modulation characteristics	$\Delta F1_{avg}$	—	251.5	—	kHz
	Min. $\Delta F1_{max}$ (for at least 99.9% of all $\Delta F1_{max}$ )	—	241.4	—	kHz
In-band emissions	$\pm 2$ MHz offset	—	-36	—	dBm
	$\pm 3$ MHz offset	—	-43	—	dBm
	$> \pm 3$ MHz offset	—	-43	—	dBm

Table 21: Bluetooth LE - Transmitter Characteristics - 500 Kbps

Parameter	Description	Min	Typ	Max	Unit
Carrier frequency offset and drift	Max. $ f_n _{n=0, 1, 2, 3, \dots k}$	—	2.5	—	kHz
	Max. $ f_0 - f_n _{n=1, 2, 3, \dots k}$	—	0.8	—	kHz
	$ f_0 - f_3 $	—	0.3	—	kHz
	Max. $ f_n - f_{n-3} _{n=7, 8, 9, \dots k}$	—	1.2	—	kHz
Modulation characteristics	$\Delta F2_{avg}$	—	231.7	—	kHz
	Min. $\Delta F2_{max}$ (for at least 99.9% of all $\Delta F2_{max}$ )	—	220.0	—	kHz
In-band emissions	$\pm 2$ MHz offset	—	-30	—	dBm
	$\pm 3$ MHz offset	—	-34	—	dBm
	$> \pm 3$ MHz offset	—	-37	—	dBm

Note that the In-band emissions in Table 18 and Table 21 above are tested at 15 dBm of TX power. However, the test result still meets the Bluetooth SIG standard even if the TX power is increased up to 20 dBm.

## 7.1.2 Bluetooth LE RF Receiver (RX) Characteristics

Table 22: Bluetooth LE - Receiver Characteristics - 1 Mbps

Parameter	Description	Min	Typ	Max	Unit	
Sensitivity @30.8% PER	—	—	-98.0	—	dBm	
Maximum received signal @30.8% PER	—	—	8	—	dBm	
C/I and receiver selectivity performance	Co-channel	$F = F_0$ MHz	—	4	—	dB
	Adjacent channel	$F = F_0 + 1$ MHz	—	2	—	dB
		$F = F_0 - 1$ MHz	—	0	—	dB
		$F = F_0 + 2$ MHz	—	-29	—	dB
		$F = F_0 - 2$ MHz	—	-29	—	dB
		$F = F_0 + 3$ MHz	—	-35	—	dB
		$F = F_0 - 3$ MHz	—	-36	—	dB
		$F \geq F_0 + 4$ MHz	—	-30	—	dB
	$F \leq F_0 - 4$ MHz	—	-36	—	dB	
Image frequency	—	—	-30	—	dB	
Adjacent channel to image frequency	$F = F_{image} + 1$ MHz	—	-32	—	dB	
	$F = F_{image} - 1$ MHz	—	-35	—	dB	
Out-of-band blocking performance	30 MHz ~ 2000 MHz	—	-16	—	dBm	
	2003 MHz ~ 2399 MHz	—	-12	—	dBm	
	2484 MHz ~ 2997 MHz	—	-16	—	dBm	
	3000 MHz ~ 12.75 GHz	—	0	—	dBm	
Intermodulation	—	—	-35	—	dBm	

Table 23: Bluetooth LE - Receiver Characteristics - 2 Mbps

Parameter	Description	Min	Typ	Max	Unit	
Sensitivity @30.8% PER	—	—	-95.0	—	dBm	
Maximum received signal @30.8% PER	—	—	8	—	dBm	
C/I and receiver selectivity performance	Co-channel	$F = F_0$ MHz	—	5	—	dB
	Adjacent channel	$F = F_0 + 2$ MHz	—	1	—	dB
		$F = F_0 - 2$ MHz	—	-2	—	dB
		$F = F_0 + 4$ MHz	—	-27	—	dB
		$F = F_0 - 4$ MHz	—	-32	—	dB
		$F = F_0 + 6$ MHz	—	-33	—	dB
		$F = F_0 - 6$ MHz	—	-36	—	dB
		$F \geq F_0 + 8$ MHz	—	-36	—	dB
	$F \leq F_0 - 8$ MHz	—	-36	—	dB	
Image frequency	—	—	-26	—	dB	
Adjacent channel to image frequency	$F = F_{image} + 2$ MHz	—	-33	—	dB	
	$F = F_{image} - 2$ MHz	—	1	—	dB	
Out-of-band blocking performance	30 MHz ~ 2000 MHz	—	-17	—	dBm	
	2003 MHz ~ 2399 MHz	—	-27	—	dBm	
	2484 MHz ~ 2997 MHz	—	-17	—	dBm	

Cont'd on next page

Table 23 – cont'd from previous page

Parameter	Description	Min	Typ	Max	Unit
	3000 MHz ~ 12.75 GHz	—	0	—	dBm
Intermodulation	—	—	-27	—	dBm

Table 24: Bluetooth LE - Receiver Characteristics - 125 Kbps

Parameter	Description	Min	Typ	Max	Unit	
Sensitivity @30.8% PER	—	—	-105.5	—	dBm	
Maximum received signal @30.8% PER	—	—	8	—	dBm	
C/I and receiver selectivity performance	Co-channel	$F = F_0 \text{ MHz}$	—	0	—	dB
	Adjacent channel	$F = F_0 + 1 \text{ MHz}$	—	-4	—	dB
		$F = F_0 - 1 \text{ MHz}$	—	-6	—	dB
		$F = F_0 + 2 \text{ MHz}$	—	-31	—	dB
		$F = F_0 - 2 \text{ MHz}$	—	-34	—	dB
		$F = F_0 + 3 \text{ MHz}$	—	-39	—	dB
		$F = F_0 - 3 \text{ MHz}$	—	-48	—	dB
		$F \geq F_0 + 4 \text{ MHz}$	—	-35	—	dB
		$F \leq F_0 - 4 \text{ MHz}$	—	-48	—	dB
	Image frequency	—	—	-39	—	dB
Adjacent channel to image frequency	$F = F_{image} + 1 \text{ MHz}$	—	-38	—	dB	
	$F = F_{image} - 1 \text{ MHz}$	—	-39	—	dB	

Table 25: Bluetooth LE - Receiver Characteristics - 500 Kbps

Parameter	Description	Min	Typ	Max	Unit	
Sensitivity @30.8% PER	—	—	-101.5	—	dBm	
Maximum received signal @30.8% PER	—	—	8	—	dBm	
C/I and receiver selectivity performance	Co-channel	$F = F_0 \text{ MHz}$	—	2	—	dB
	Adjacent channel	$F = F_0 + 1 \text{ MHz}$	—	-1	—	dB
		$F = F_0 - 1 \text{ MHz}$	—	-4	—	dB
		$F = F_0 + 2 \text{ MHz}$	—	-28	—	dB
		$F = F_0 - 2 \text{ MHz}$	—	-29	—	dB
		$F = F_0 + 3 \text{ MHz}$	—	-38	—	dB
		$F = F_0 - 3 \text{ MHz}$	—	-41	—	dB
		$F \geq F_0 + 4 \text{ MHz}$	—	-33	—	dB
		$F \leq F_0 - 4 \text{ MHz}$	—	-41	—	dB
	Image frequency	—	—	-33	—	dB
Adjacent channel to image frequency	$F = F_{image} + 1 \text{ MHz}$	—	-36	—	dB	
	$F = F_{image} - 1 \text{ MHz}$	—	-38	—	dB	

## 7.2 802.15.4 Radio

Table 26: 802.15.4 RF Characteristics

Name	Description
Center frequency range of operating channel	2405~2480 MHz

<sup>1</sup> Zigbee in the 2.4 GHz range supports 16 channels at 5 MHz spacing from channel 11 to channel 26.

### 7.2.1 802.15.4 RF Transmitter (TX) Characteristics

Table 27: 802.15.4 Transmitter Characteristics - 250 Kbps

Parameter	Min	Typ	Max	Unit
RF transmit power range	-25.5	—	18.5	dBm
EVM	—	3.8%	—	—

### 7.2.2 802.15.4 RF Receiver (RX) Characteristics

Table 28: 802.15.4 Receiver Characteristics - 250 Kbps

Parameter	Description	Min	Typ	Max	Unit	
Sensitivity @1% PER	—	—	-101.5	—	dBm	
Maximum received signal @1% PER	—	—	8	—	dBm	
Relative jamming level	Adjacent channel	F = FO + 5 MHz	—	31	—	dB
		F = FO - 5 MHz	—	43	—	dB
	Alternate channel	F = FO + 10 MHz	—	49	—	dB
		F = FO - 10 MHz	—	54	—	dB

# 8 Module Schematics

This is the reference design of the module.

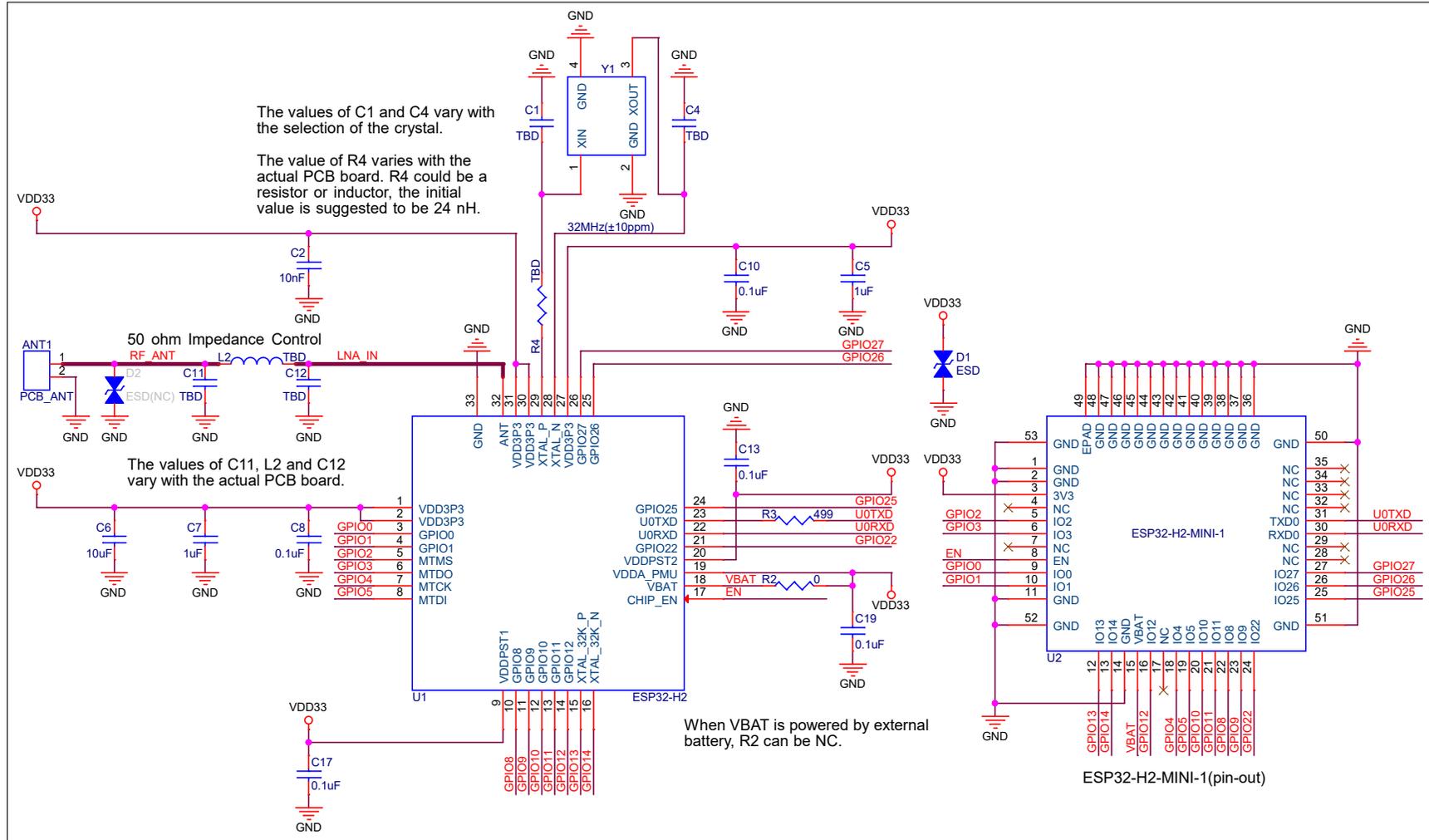


Figure 5: ESP32-H2-MINI-1 Schematics

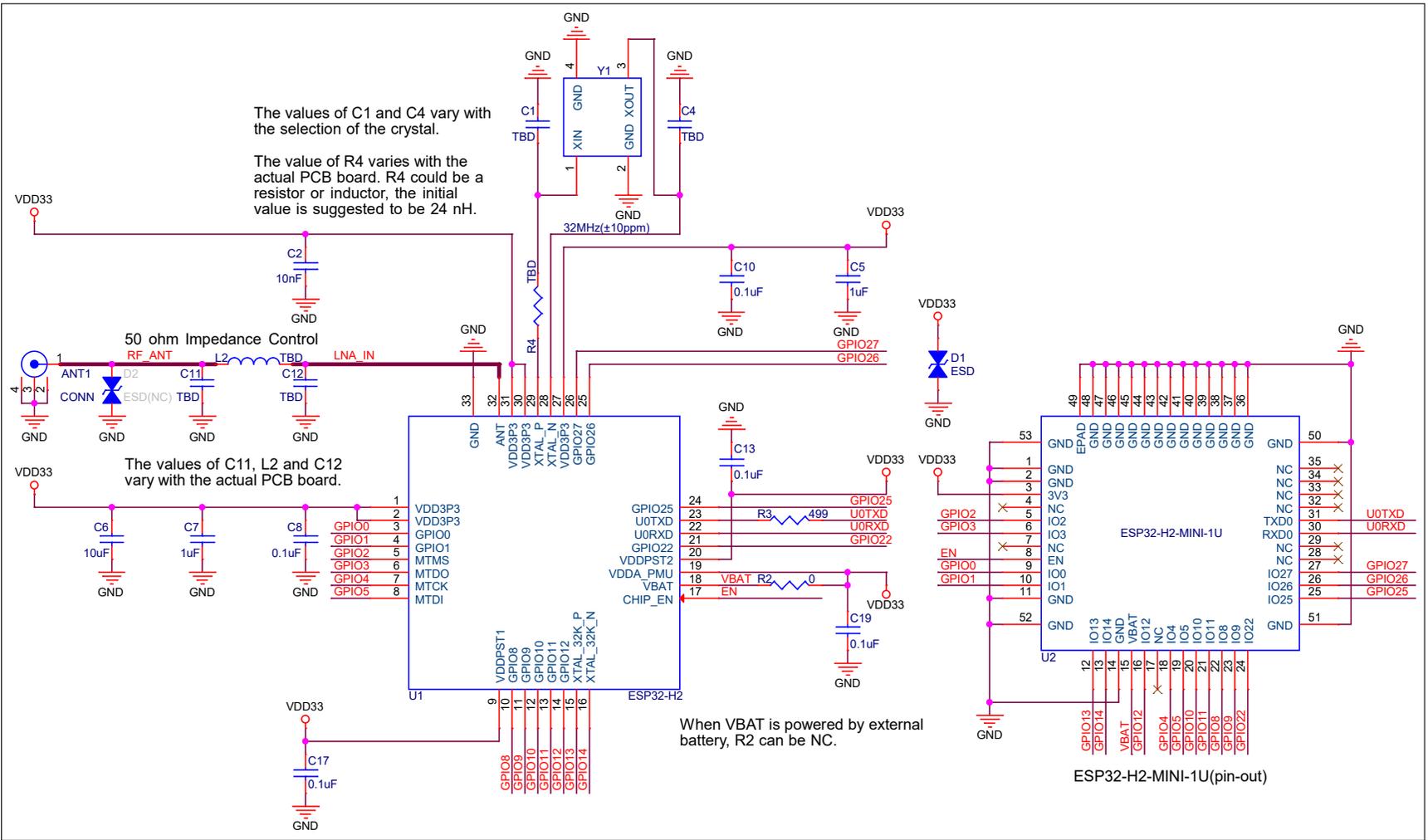


Figure 6: ESP32-H2-MINI-1U Schematics

## 9 Peripheral Schematics

This is the typical application circuit of the module connected with peripheral components (for example, power supply, antenna, reset button, JTAG interface, and UART interface).

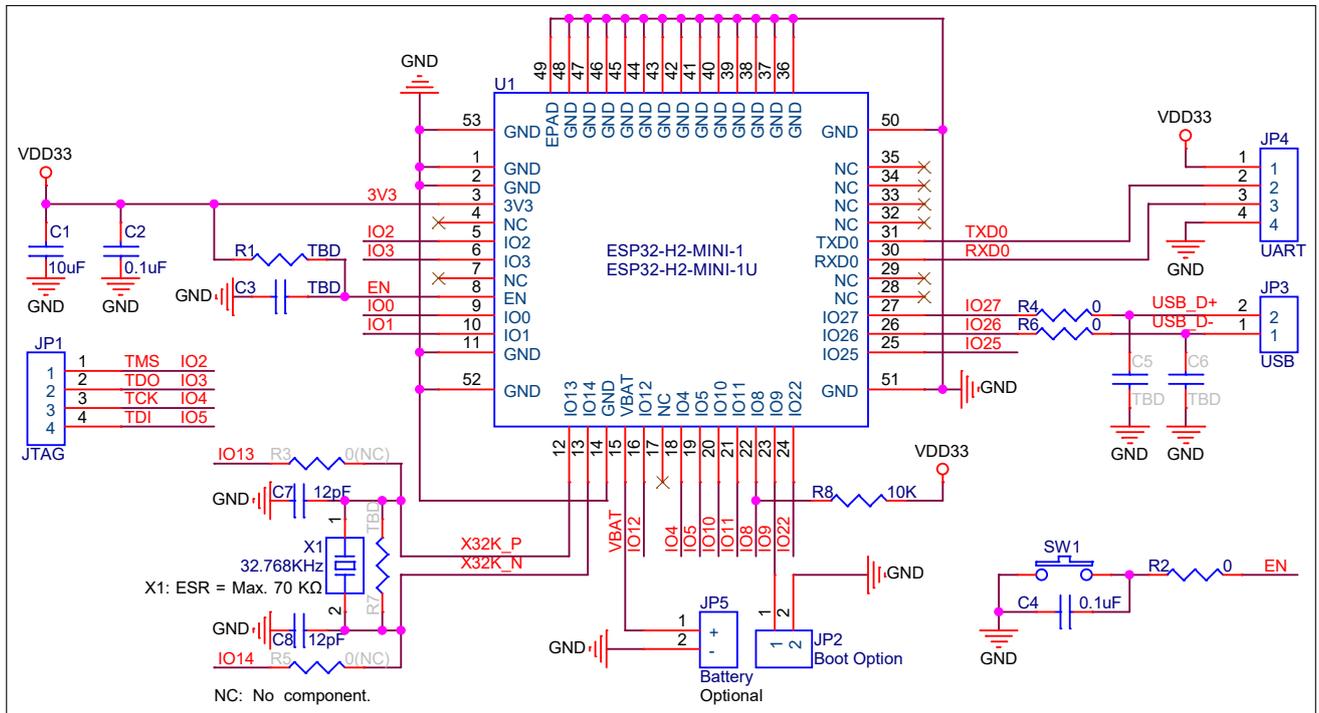


Figure 7: Peripheral Schematics

- Soldering the EPAD to the ground of the base board is not a must, however, it can optimize thermal performance. If you choose to solder it, please apply the correct amount of soldering paste. Too much soldering paste may increase the gap between the module and the baseboard. As a result, the adhesion between other pins and the baseboard may be poor.
- To ensure that the power supply to the ESP32-H2 chip is stable during power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually  $R = 10\text{ k}\Omega$  and  $C = 1\ \mu\text{F}$ . However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset sequence timing of the chip. For ESP32-H2's power-up and reset sequence timing diagram, please refer to [ESP32-H2 Series Datasheet](#) > Section *Power Supply*.

# 10 Physical Dimensions

## 10.1 Module Dimensions

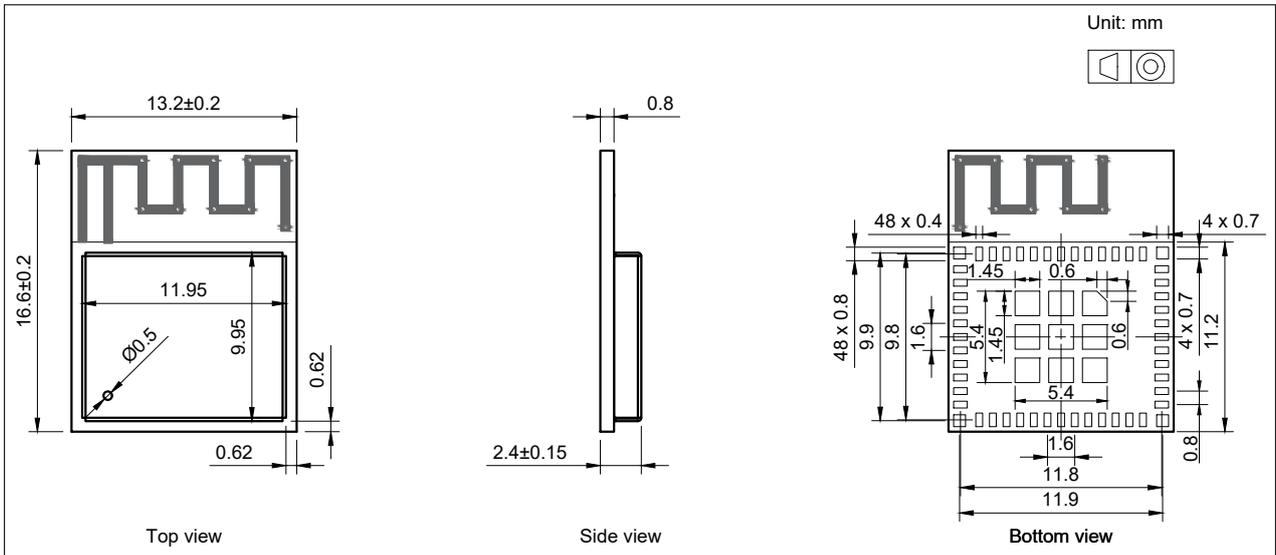


Figure 8: ESP32-H2-MINI-1 Physical Dimensions

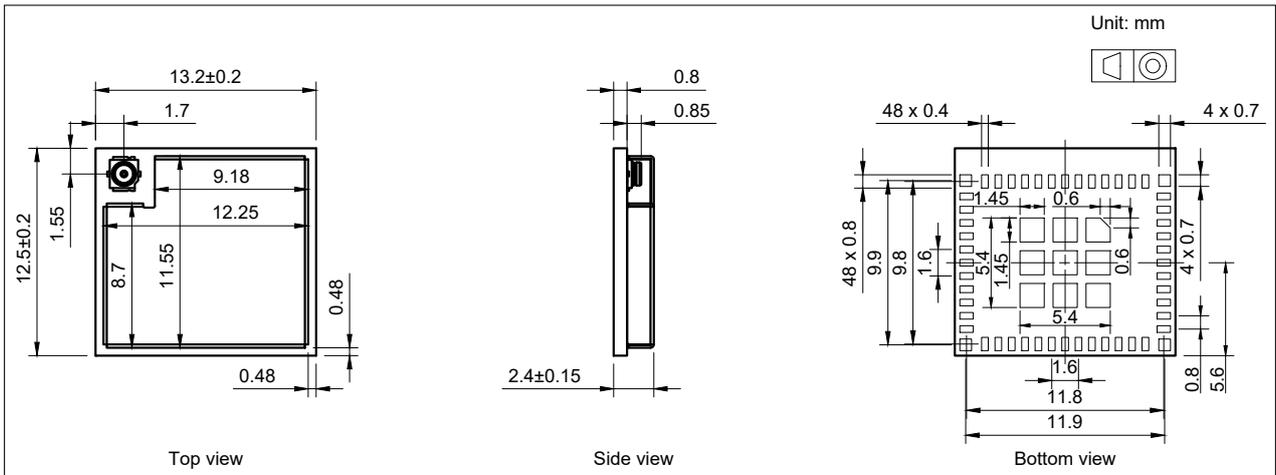


Figure 9: ESP32-H2-MINI-1U Physical Dimensions

**Note:**

For information about tape, reel, and product marking, please refer to [Espressif Module Packaging Information](#).

## 10.2 Dimensions of External Antenna Connector

ESP32-H2-MINI-1U uses the third generation external antenna connector as shown in Figure 10 *Dimensions of External Antenna Connector*. This connector is compatible with the following connectors:

- W.FL Series connector from Hirose
- MHF III connector from I-PEX
- AMMC connector from Amphenol

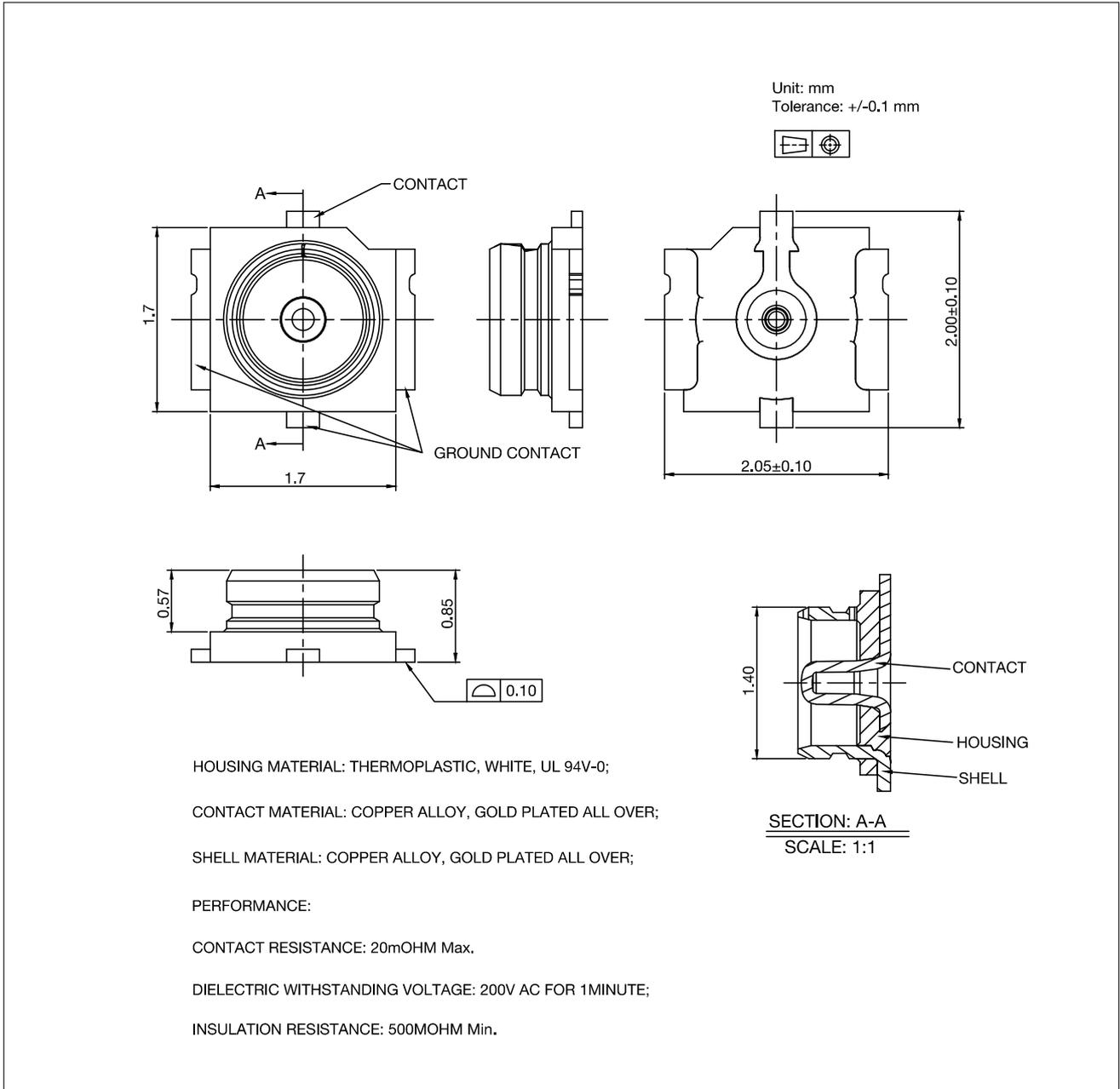


Figure 10: Dimensions of External Antenna Connector

# 11 PCB Layout Recommendations

## 11.1 PCB Land Pattern

This section provides the following resources for your reference:

- Figure 11 *ESP32-H2-MINI-1 Recommended PCB Land Pattern* and Figure 12 *ESP32-H2-MINI-1U Recommended PCB Land Pattern*: the recommended PCB land patterns with all the dimensions needed for PCB design.
- Source files for [ESP32-H2-MINI-1](#) and [ESP32-H2-MINI-1U](#): the recommended PCB land patterns to measure dimensions not covered in Figure 11 and Figure 12. You can view the source files with [Autodesk Viewer](#).
- 3D models of [ESP32-H2-MINI-1](#) and [ESP32-H2-MINI-1U](#): the .STEP format file. Please make sure that you download the 3D model file in .STEP format (beware that some browsers might add .txt).

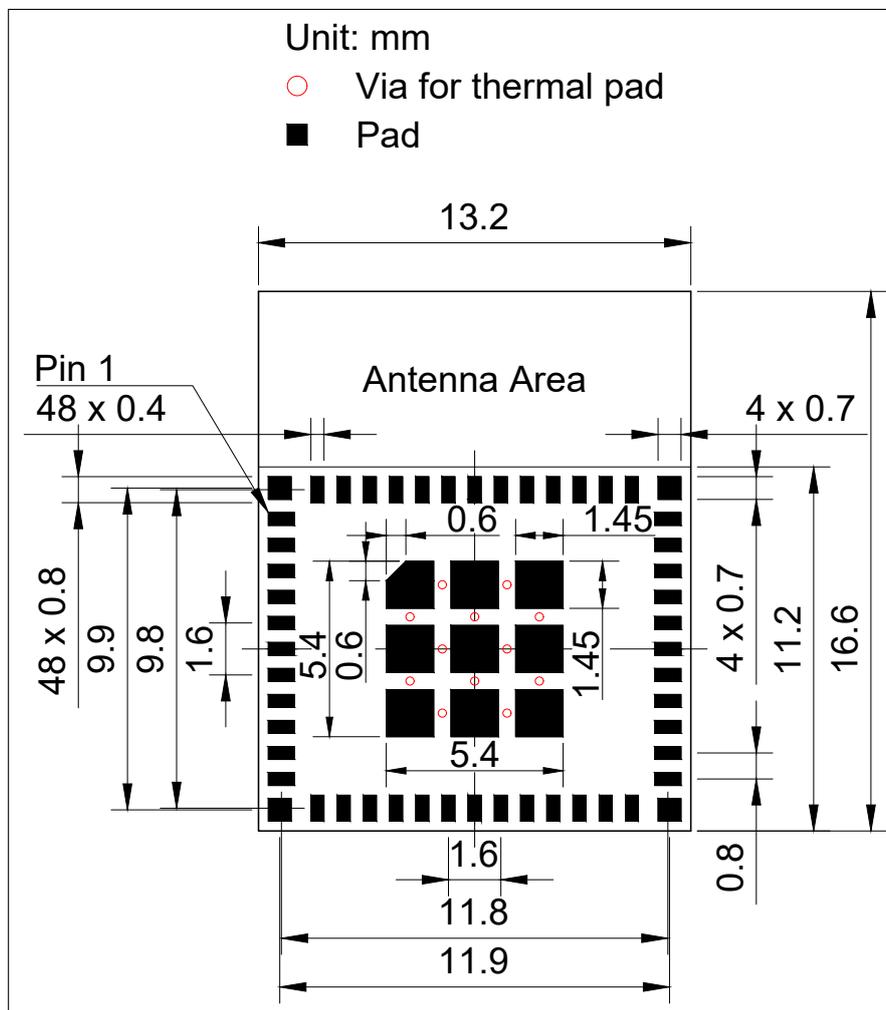


Figure 11: ESP32-H2-MINI-1 Recommended PCB Land Pattern



## 12 Product Handling

### 12.1 Storage Conditions

The products sealed in moisture barrier bags (MBB) should be stored in a non-condensing atmospheric environment of  $< 40\text{ }^{\circ}\text{C}$  and 90%RH. The module is rated at the moisture sensitivity level (MSL) of 3.

After unpacking, the module must be soldered within 168 hours with the factory conditions  $25\pm 5\text{ }^{\circ}\text{C}$  and 60%RH. If the above conditions are not met, the module needs to be baked.

### 12.2 Electrostatic Discharge (ESD)

- Human body model (HBM):  $\pm 2000\text{ V}$
- Charged-device model (CDM):  $\pm 500\text{ V}$

### 12.3 Soldering Profile

#### 12.3.1 Reflow Profile

Solder the module in a single reflow.

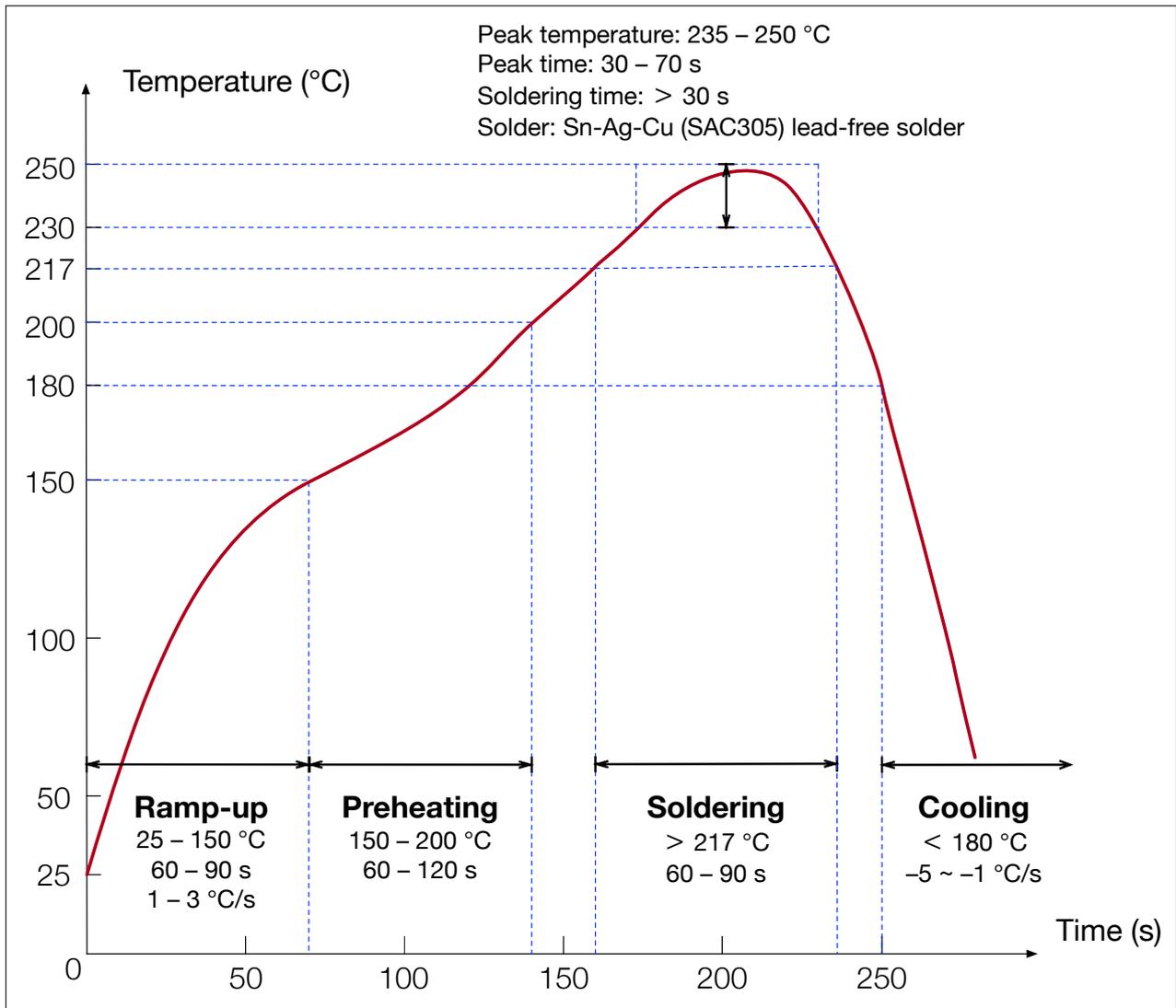


Figure 13: Reflow Profile

## 12.4 Ultrasonic Vibration

Avoid exposing Espressif modules to vibration from ultrasonic equipment, such as ultrasonic welders or ultrasonic cleaners. This vibration may induce resonance in the in-module crystal and lead to its malfunction or even failure. As a consequence, **the module may stop working or its performance may deteriorate.**

## Related Documentation and Resources

### Related Documentation

- [ESP32-H2 Series Datasheet](#) – Specifications of the ESP32-H2 hardware.
- [ESP32-H2 Technical Reference Manual](#) – Detailed information on how to use the ESP32-H2 memory and peripherals.
- [ESP32-H2 Hardware Design Guidelines](#) – Guidelines on how to integrate the ESP32-H2 into your hardware product.
- [ESP32-H2 Series SoC Errata](#) – Descriptions of known errors in ESP32-H2 series of SoCs.
- *Certificates*  
<https://espressif.com/en/support/documents/certificates>
- *ESP32-H2 Product/Process Change Notifications (PCN)*  
<https://espressif.com/en/support/documents/pcns?keys=ESP32-H2>
- *ESP32-H2 Advisories* – Information on security, bugs, compatibility, component reliability.  
<https://espressif.com/en/support/documents/advisories?keys=ESP32-H2>
- *Documentation Updates and Update Notification Subscription*  
<https://espressif.com/en/support/download/documents>

### Developer Zone

- [ESP-IDF Programming Guide for ESP32-H2](#) – Extensive documentation for the ESP-IDF development framework.
- *ESP-IDF* and other development frameworks on GitHub.  
<https://github.com/espressif>
- *ESP32 BBS Forum* – Engineer-to-Engineer (E2E) Community for Espressif products where you can post questions, share knowledge, explore ideas, and help solve problems with fellow engineers.  
<https://esp32.com/>
- *The ESP Journal* – Best Practices, Articles, and Notes from Espressif folks.  
<https://blog.espressif.com/>
- See the tabs *SDKs and Demos, Apps, Tools, AT Firmware*.  
<https://espressif.com/en/support/download/sdks-demos>

### Products

- *ESP32-H2 Series SoCs* – Browse through all ESP32-H2 SoCs.  
<https://espressif.com/en/products/socs?id=ESP32-H2>
- *ESP32-H2 Series Modules* – Browse through all ESP32-H2-based modules.  
<https://espressif.com/en/products/modules?id=ESP32-H2>
- *ESP32-H2 Series DevKits* – Browse through all ESP32-H2-based devkits.  
<https://espressif.com/en/products/devkits?id=ESP32-H2>
- *ESP Product Selector* – Find an Espressif hardware product suitable for your needs by comparing or applying filters.  
<https://products.espressif.com/#/product-selector?language=en>

### Contact Us

- See the tabs *Sales Questions, Technical Enquiries, Circuit Schematic & PCB Design Review, Get Samples* (Online stores), *Become Our Supplier, Comments & Suggestions*.  
<https://espressif.com/en/contact-us/sales-questions>

## Revision History

Date	Version	Release notes
2024-11-08	v1.0	<ul style="list-style-type: none"><li>• Official release</li><li>• Improved the content, formatting, structure, and wording of the whole document</li></ul>
2023-10-17	v0.6	<ul style="list-style-type: none"><li>• Updated the description about Boot Mode Control in Section <i>Strapping Pins</i>.</li><li>• Updated the descriptions about resources offered in Section <a href="#">11.1 PCB Land Pattern</a>.</li><li>• Updated measurements in Table <a href="#">15</a> and <a href="#">16</a>.</li></ul>
2023-05-24	v0.5	Preliminary release



## Disclaimer and Copyright Notice

Information in this document, including URL references, is subject to change without notice.

ALL THIRD PARTY'S INFORMATION IN THIS DOCUMENT IS PROVIDED AS IS WITH NO WARRANTIES TO ITS AUTHENTICITY AND ACCURACY.

NO WARRANTY IS PROVIDED TO THIS DOCUMENT FOR ITS MERCHANTABILITY, NON-INFRINGEMENT, FITNESS FOR ANY PARTICULAR PURPOSE, NOR DOES ANY WARRANTY OTHERWISE ARISING OUT OF ANY PROPOSAL, SPECIFICATION OR SAMPLE.

All liability, including liability for infringement of any proprietary rights, relating to use of information in this document is disclaimed. No licenses express or implied, by estoppel or otherwise, to any intellectual property rights are granted herein.

The Wi-Fi Alliance Member logo is a trademark of the Wi-Fi Alliance. The Bluetooth logo is a registered trademark of Bluetooth SIG.

All trade names, trademarks and registered trademarks mentioned in this document are property of their respective owners, and are hereby acknowledged.

Copyright © 2024 Espressif Systems (Shanghai) Co., Ltd. All rights reserved.

[www.espressif.com](http://www.espressif.com)